



## Material Content Data Sheet



<b>Sales Product Name</b>		BCR 08PN H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000846160						
<b>Package</b>		PG-SOT363-6-1		<b>Weight*</b>		6.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		16	
	noble metal	gold	7440-57-5	0.010	0.16		1595	
	inorganic material	silicon	7440-21-3	0.086	1.36	1.52	13623	15234
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		459	
	non noble metal	chromium	7440-47-3	0.009	0.14		1376	
	non noble metal	copper	7440-50-8	2.869	45.67	45.87	456636	458563
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1628	1628
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4817	
	plastics	epoxy resin	-	0.651	10.36		103564	
	inorganic material	silicondioxide	60676-86-0	2.346	37.33	48.17	373312	481693
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33936	33936
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8946	8946
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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